

Fig. 1

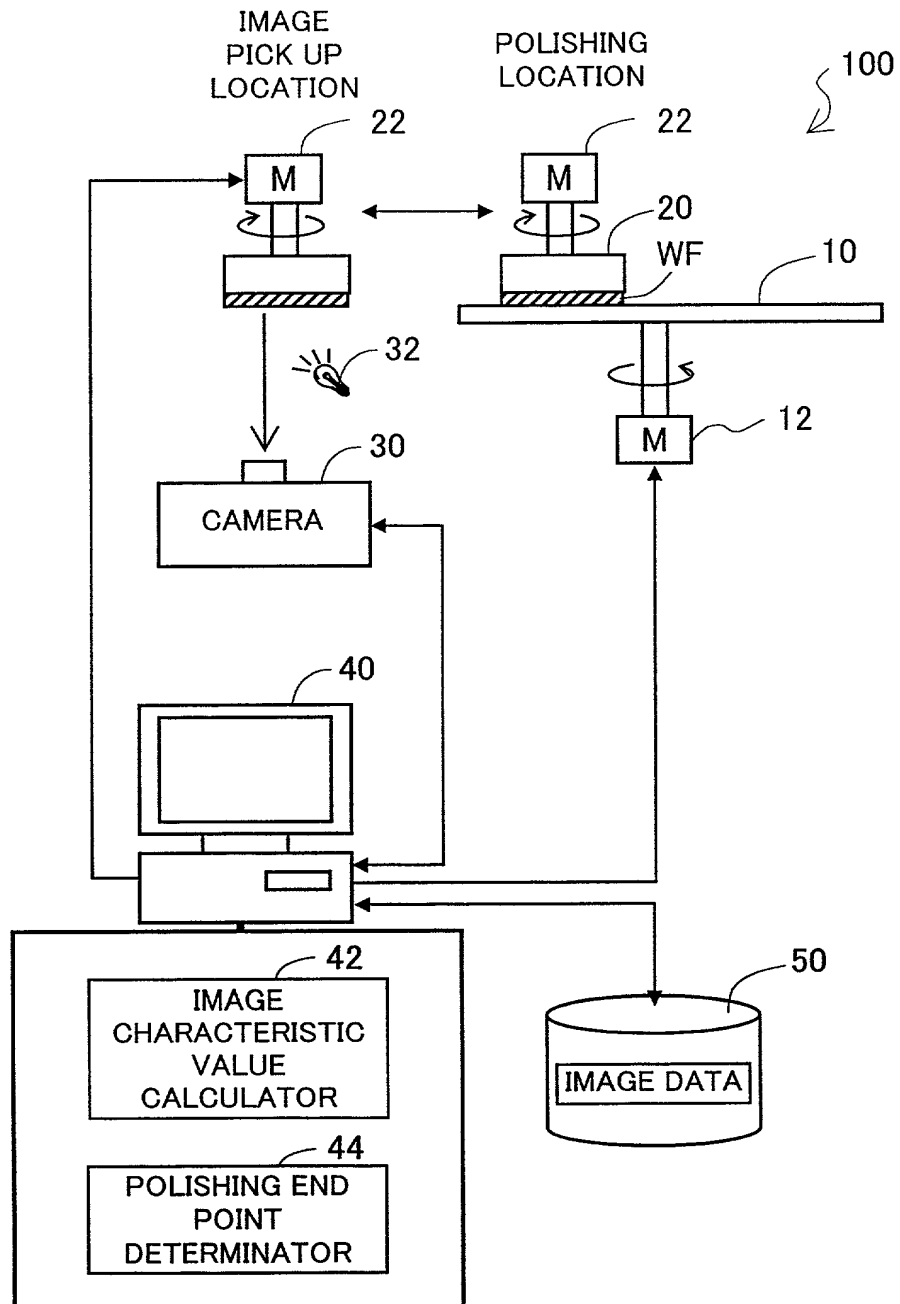
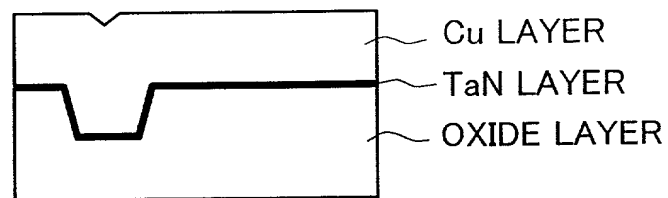
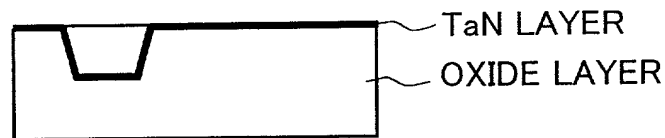


Fig. 2A FORMING Cu LAYER



REMOVING Cu LAYER

Fig. 2B FIRST CMP PROCESS



DELETING TaN
SURFACE LAYER

Fig. 2C SECOND CMP PROCESS



Fig. 3

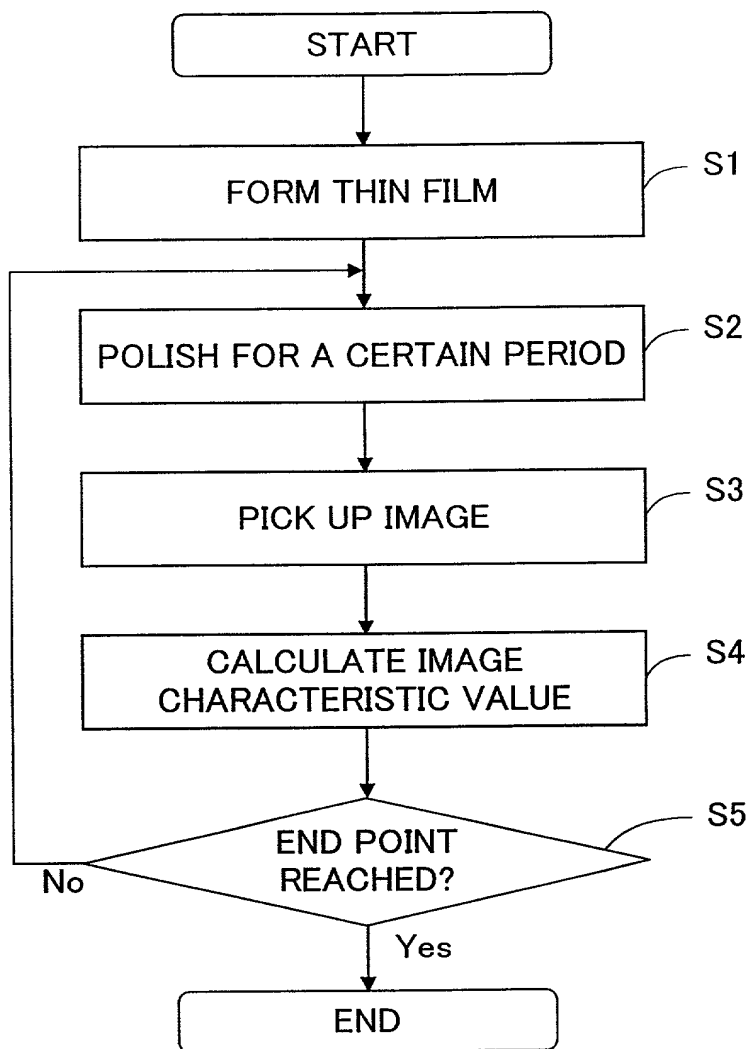


Fig. 4A

BEFORE POLISHING

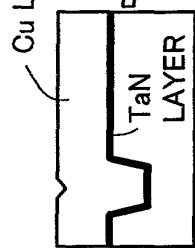


Fig. 4B

PLANARIZING
Cu LAYER

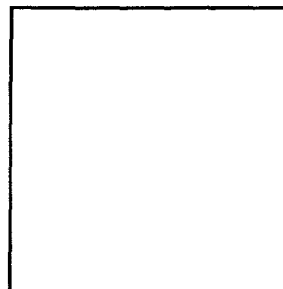
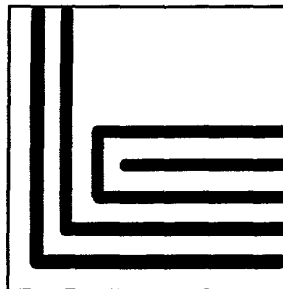
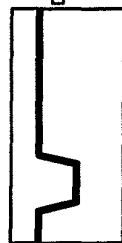


Fig. 4C

STARTING TO
DETECT WIRING
PATTERN

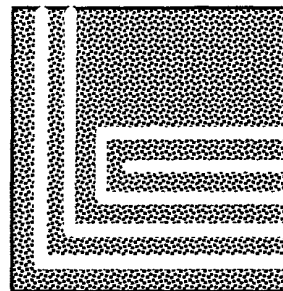
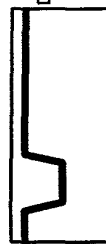


Fig. 4D

APPROPRIATE
POLISHING

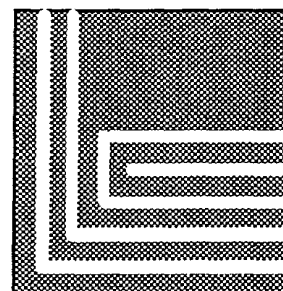
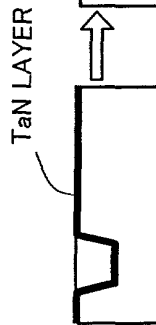


Fig. 4E

EXCESSIVE
POLISHING

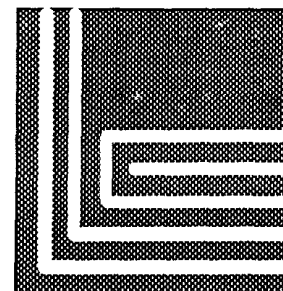


Fig. 5

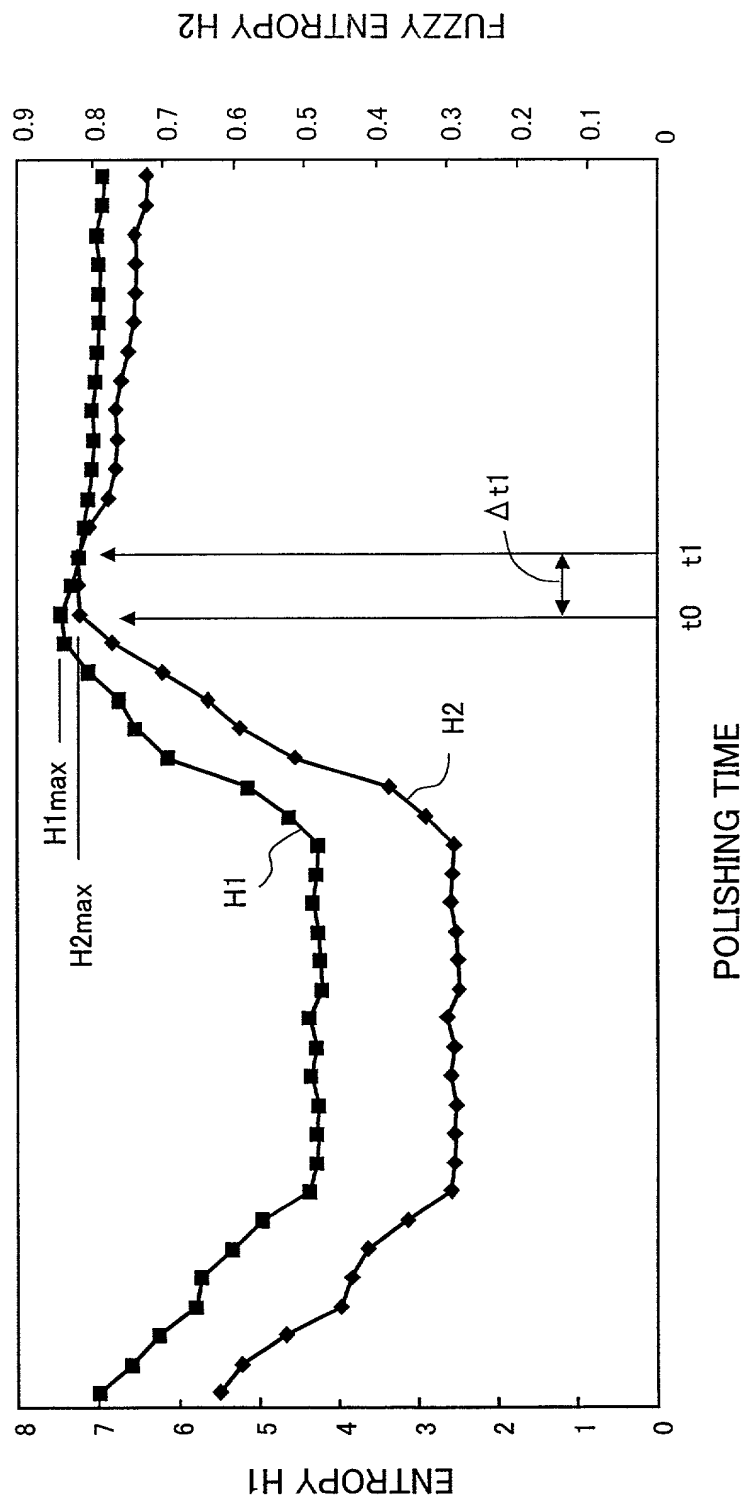
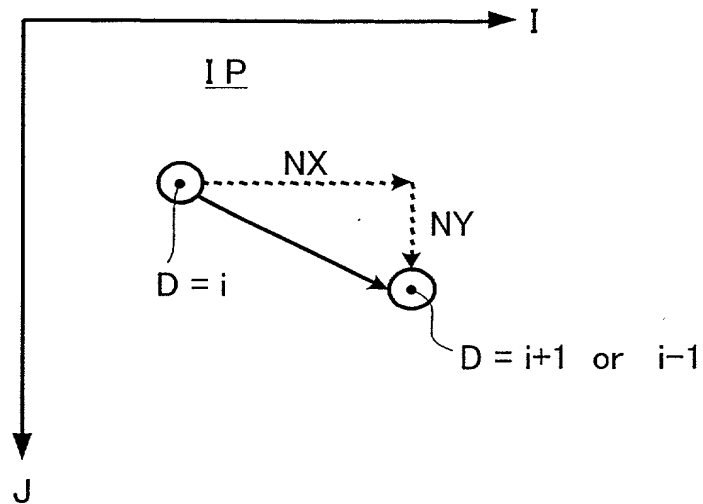


Fig.6

CALCULATION OF HISTOGRAMS $G(i)$,
 $P(i)$ USED IN DIFFERENCE STATISTIC
OF GRAY IMAGE



HYSTOGRAM $G(i)$:

Probability that an absolute value of a difference of image values D of two pixels separated by (NX, NY) has a value of i .

$$P(i) = G(i+1)$$

Fig. 7

